

### NOT RECOMMENDED FOR NEW DESIGN **CONTACT US**



DMTH4001SPS

### 40V +175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

## **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Tc = +25°C	
40V	$1.0 m\Omega$ @ $V_{GS} = 10V$	225A	

## **Description and Applications**

This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

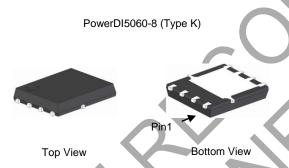
- **Engine Management Systems**
- **Body Control Electronics**
- **DC-DC Converters**

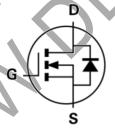
### **Features**

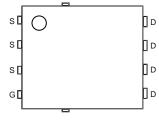
- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching (UIS) Test in Production -Ensures More Reliable and Robust End Application
- Thermally Efficient Package-Cooler Running Applications
- High Conversion Efficiency
  - Low R<sub>DS(ON)</sub> Minimizes On State Losses
- <1.1mm Package Profile Ideal for Thin Applications
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/
- An Automotive-Compliant Part is Available Under Separate Datasheet (DMTH4001SPSQ)

### **Mechanical Data**

- Package: PowerDI®5060-8
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
  Terminal Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.097 grams (Approximate)







Internal Schematic

Top View Pin Configuration

## Ordering Information (Note 4)

Dart Number	Pookage	Packing		
Part Number	Package	Qty.	Carrier	
DMTH4001SPS-13	PowerDI5060-8 (Type K)	2,500	Tape & Reel	

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**



The Manufacturer's Marking TH4001SS = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 21 = 2021) WW = Week Code (01 to 53)

PowerDI is a registered trademark of Diodes Incorporated.



# **Maximum Ratings** (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	VDSS	40	V	
Gate-Source Voltage	Vgss	±20	V	
Continuous Drain Current, $V_{GS} = 10V$ (Note 6) $T_{C} = +25^{\circ}C$ $T_{C} = +100^{\circ}C$		lD	225 160	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	900	Α	
Continuous Body Diode Forward Current (Note 6) T <sub>C</sub> = +25°C		ls	200	Α
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)	Ism	900	Α	
Avalanche Current, L = 0.1mH	las	93.8	Α	
Avalanche Energy, L = 0.1mH	Eas	440	mJ	

# **Thermal Characteristics**

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C	Pb	3.1	W
Thermal Resistance, Junction to Ambient (Note 5)			48	°C/W
Total Power Dissipation (Note 6)	$T_C = +25^{\circ}C$	P <sub>D</sub>	187.5	W
Thermal Resistance, Junction to Case (Note 6)		Rejc	0.8	°C/W
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +175	°C

# Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BVDSS	40	1		V	$V_{GS} = 0V$ , $I_D = 1mA$	
Zero Gate Voltage Drain Current	IDSS	_		1	μA	$V_{DS} = 32V$ , $V_{GS} = 0V$	
Gate-Source Leakage	IGSS			±100	nA	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	2	2.61	4	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain-Source On-Resistance	RDS(ON)		0.73	1.0	mΩ	$V_{GS} = 10V, I_{D} = 30A$	
Diode Forward Voltage	VsD		0.7	1.3	V	V <sub>G</sub> S = 0V, I <sub>S</sub> = 20A	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	\Z	10787	14023		V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V, f = 1MHz	
Output Capacitance	Coss		3929	5108	pF		
Reverse Transfer Capacitance	Crss	_	156	203			
Gate Resistance	Rg	_	3.71	10	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	144	187			
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	85	111	nC	V <sub>DD</sub> = 20V. I <sub>D</sub> = 50A	
Gate-Source Charge	Qgs	_	40	_	IIC	VDD = 20V, ID = 50A	
Gate-Drain Charge	$Q_{gd}$	_	24	_			
Turn-On Delay Time	t <sub>D(ON)</sub>	_	11	_			
Turn-On Rise Time	t <sub>R</sub>	_	44	_		$V_{DD} = 20V, V_{GS} = 10V,$ $I_{D} = 50A, R_{g} = 2.5\Omega$	
Turn-Off Delay Time	tD(OFF)	_	85	_	ns		
Turn-Off Fall Time	tF	_	38	_			
Reverse Recovery Time	trr		68	_	ns	In - 15 A di/dt - 100 A/u a	
Reverse Recovery Charge	Q <sub>RR</sub>	_	110	_	nC	I <sub>F</sub> = 15A, di/dt = 100A/μs	

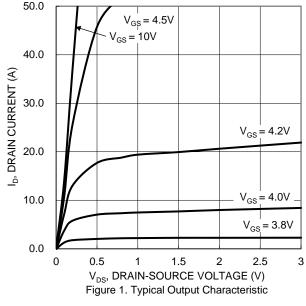
Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.

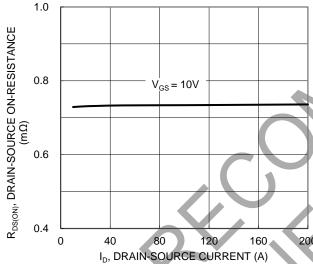
<sup>6.</sup> Thermal resistance from junction to soldering point (on the exposed drain pad).7. Short duration pulse test used to minimize self-heating effect.

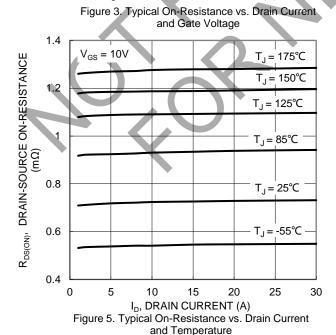
<sup>8.</sup> Guaranteed by design. Not subject to product testing.

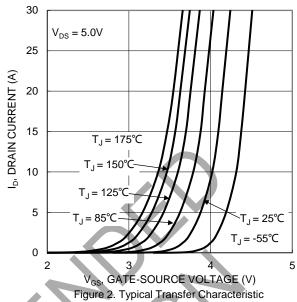


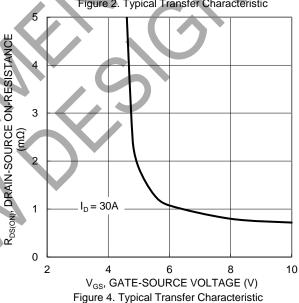












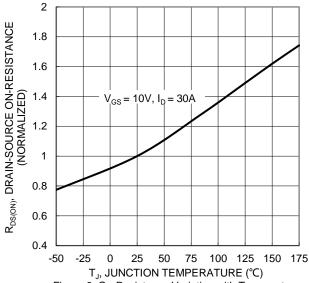


Figure 6. On-Resistance Variation with Temperature





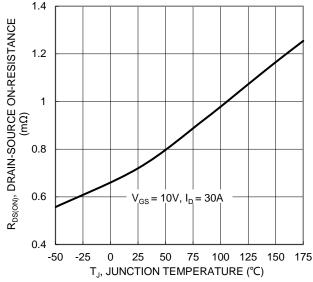
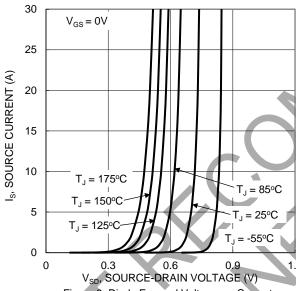
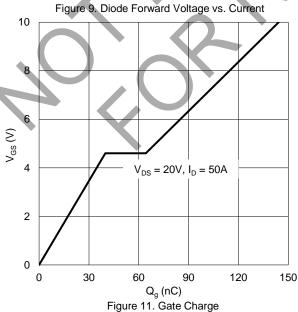
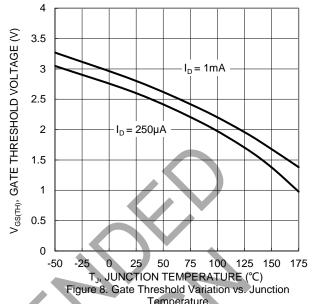
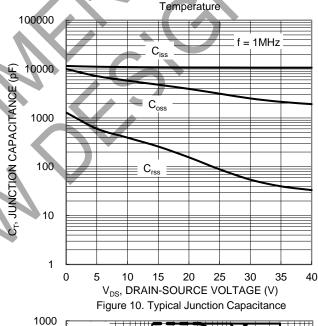


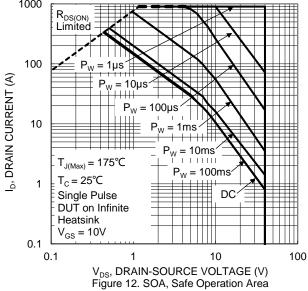
Figure 7. On-Resistance Variation with Temperature













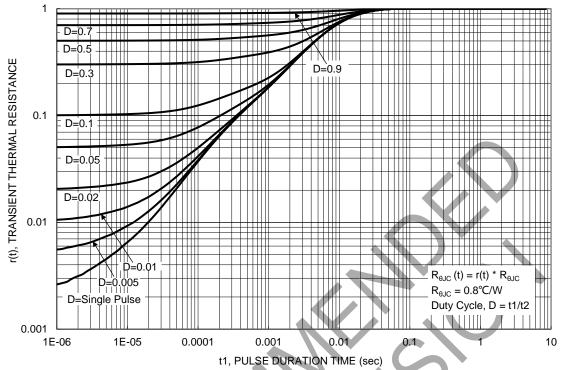


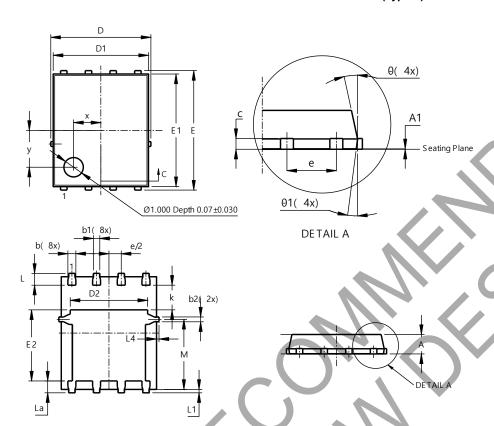
Figure 13. Transient Thermal Resistance



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### PowerDI5060-8 (Type K)

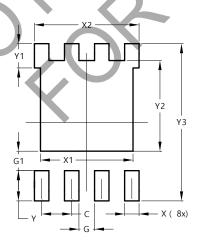


PowerDI5060-8 (Type K)					
Dim	Min	Max	Тур		
A	0.90	1.10	1.00		
A1	0	0.05	0.02		
b	0.33	0.51	0.41		
b1	0.300	0.366	0.333		
b2	0.20	0.35	0.25		
C	0.23	0.33	0.277		
D	5	.15 BS0	<u> </u>		
D1	4.85	4.95	4.90		
D2	1		3.98		
E	6	.15 BS0			
E1	5.75	5.85	5.80		
E2	3.56	3.725	3.66		
е	1	.27BSC	)		
k		-	1.27		
J	0.51	0.71	0.61		
La	0.51	0.675	0.61		
L1	0.05	0.20	0.175		
L4	-	-	0.125		
М	3.50	3.71	3.605		
Х	-	-	1.400		
у	-	-	1.900		
θ	10°	12°	11°		
θ1	6°	8°	7°		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

## PowerDI5060-8 (Type K)



Dimensions	Value (in mm)		
С	1.270		
G	0.660		
G1	0.820		
Х	0.610		
X1	3.910		
X2	4.420		
Y	1.270		
Y1	1.020		
Y2	3.810		
Y3	6.610		



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